

AUF3805S-7P-VB Datasheet N-Channel 60 V (D-S) 175 °C MOSFET

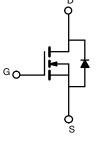
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.00163			
I _D (A)	150			
Configuration	Single			
Package	TO-263-7L			

FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 % R_g and UIS tested







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	60	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current	T _C = 25 °C	- I _D -	150		
	T _C = 125 °C		120 ^a		
Continuous source current (diode conduction) ^a		I _S	120	А	
Pulsed drain current ^b		I _{DM}	400		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	75		
Single pulse avalanche energy	L = 0.1 MH	E _{AS}	281	mJ	
Maximum power dissipation ^b	T _C = 25 °C	D-	375	W	
	T _C = 125 °C	PD	125	٧V	
Operating junction and storage temperature range	Э	T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount ^c	R _{thJA}	40	°C/W	
Junction-to-case (drain)	-to-case (drain)		0.4	0/10	

Notes

a. Package limited

b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$

c. When mounted on 1" square PCB (FR4 material)

SPECIFICATIONS ($T_C = 25 \ ^{\circ}C$,	unless other	wise noted)					
PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$		60	-	-	v
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μΑ	2.5	3.0	3.5	
Gate-source leakage	I _{GSS}	V _{DS} =	V_{DS} = 0 V, V_{GS} = ± 20 V		-	± 100	nA
Zero gate voltage drain current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	- μΑ
		V _{GS} = 0 V	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	250	μA
On-state drain current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	120	-	-	А
Drain-source on-state resistance ^a		V _{GS} = 10 V	I _D = 30 A	-	0.00163	-	
	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.00300	-	Ω
		$V_{GS} = 10 V$	I _D = 30 A, T _J = 175 °C	-	0.00360	-	
Forward transconductance b	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		-	142	-	S
Dynamic ^b							
Input capacitance	C _{iss}		V _{DS} = 25 V, f = 1 MHz	-	9100	11 900	pF
Output capacitance	C _{oss}	$V_{GS} = 0 V$		-	3550	4700	
Reverse transfer capacitance	C _{rss}			-	160	220	
Total gate charge ^c	Qg		10 V V _{DS} = 30 V, I _D = 50 A	-	123	185	nC
Gate-source charge ^c	Q _{gs}	V _{GS} = 10 V		-	40	-	
Gate-drain charge ^c	Q _{gd}			-	19	-	
Gate resistance	R _g	f = 1 MHz		4	8.6	13	Ω
Turn-on delay time ^c	t _{d(on)}				48	75	ns
Rise time ^c	t _r	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = 30 \text{ V}, \ R_{\text{L}} = 0.6 \ \Omega \\ I_{\text{D}} \cong 50 \text{ A}, \ V_{\text{GEN}} = 10 \text{ V}, \ R_{\text{g}} = 1 \ \Omega \end{array}$		-	26	40	
Turn-off delay time ^c	t _{d(off)}			-	105	160	
Fall time ^c	t _f			-	25	40	
Source-Drain Diode Ratings and Chara	cteristics ^b						
Pulsed current ^a	I _{SM}			-	-	240	А
Forward voltage	V _{SD}	I _F = 50 A, V _{GS} = 0 V		-	0.84	1.5	V
Body diode reverse recovery time	t _{rr}	I _F = 25 A, di/dt = 100 A/μs		-	100	200	ns
Body diode reverse recovery charge	Q _{rr}			-	243	500	nC
Reverse recovery fall time	t _a			-	48	-	-
Reverse recovery rise time	t _b			-	53	-	ns
Body diode peak reverse recovery current	I _{RM(REC)}			-	-4.6	-	Α

Notes

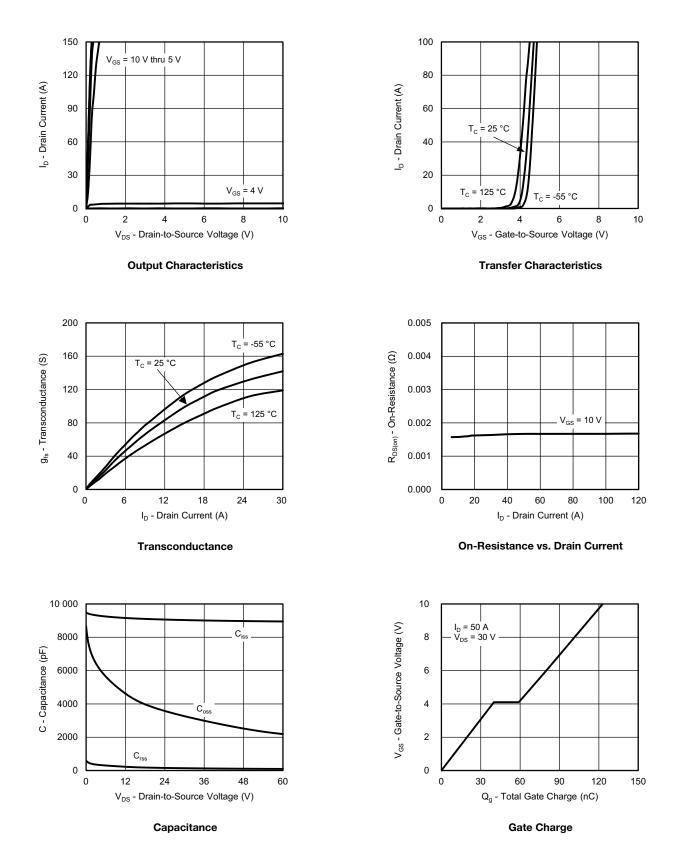
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing c. Independent of operating temperature

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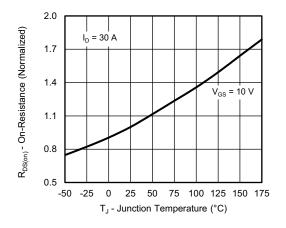


TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

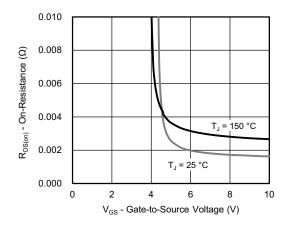




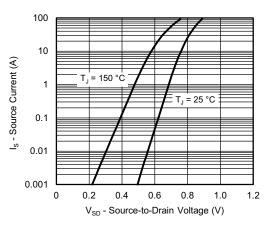
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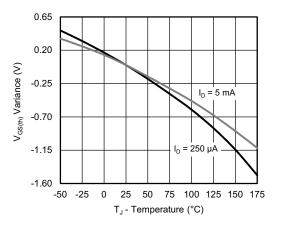
On-Resistance vs. Junction Temperature

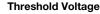


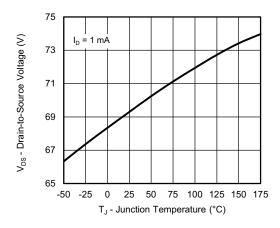
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage





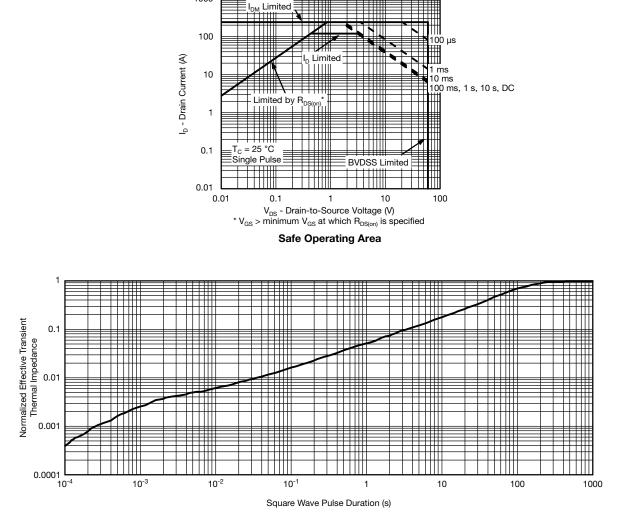


Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)

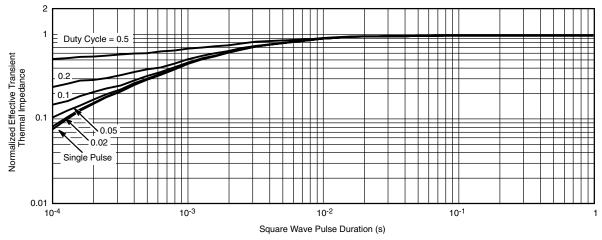
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Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions



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